

What is claimed is:

- 1       1.       A method of manufacturing an optoelectronic package having an insulating base  
2       with multiple conductive vias running through the insulating base, and having a metal  
3       cover that at least partially encloses an optoelectronic device mounted on the insulating  
4       base, the method comprising:  
5               placing a solder preform between the metal cover and the insulating base;  
6               applying pressure between the metal cover and the insulating base; and  
7               applying a current through the multiple conductive vias to heat the solder preform  
8       to melt.
- 1       2.       The method of claim 1 further comprising:  
2               metalizing a top surface of the insulating base prior to the placing of the solder  
3       preform.
- 1       3.       The method of claim 1, further comprising:  
2               allowing the solder preform to cool; and  
3               removing the pressure between the metal cover and the insulating base.
- 1       4.       The method of claim 1, further comprising:  
2               allowing the solder preform to cool; and  
3               removing the pressure between the metal cover and the insulating base.

1        5.        A method of manufacturing a TO can comprising:  
2                placing a solder preform between a metal cover and an insulating base; and  
3                applying a current to the solder preform until the solder preform melts to seal a  
4        metal cover to the insulating base.

1        6.        The method of claim 5, wherein the current is applied through conductive vias  
2        running through the insulating base.

1        7.        The method of claim 5, further comprising:  
2                creating a metallized surface on the insulating base, wherein placing the solder  
3        preform between the metal cover and the insulating base further comprises placing the  
4        solder preform in contact with the metallized surface.